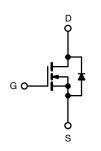
Vishay Siliconix

Power MOSFET





N-Channel MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	60	60				
R _{DS(on)} (Ω)	V _{GS} = 5 V	0.20				
Q _g (Max.) (nC)	8.	4				
Q _{gs} (nC)	2.	2.6				
Q _{gd} (nC)	6.	6.4				
Configuration	Sing	Single				

FEATURES

- Dynamic dV/dt rating
- For automatic insertion
- End stackable
- · Logic-level gate drive
- R_{DS(on)} specified at V_{GS} = 4 V and 5 V
- 175 °C operating temperature
- · Fast switching
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The 4 pin DIP package is a low cost machine-insertiable case style which can be stacked in multiple combinations on standard 0.1" pin centers. The dual drain servers as a thermal link to the mounting surface for power dissipation levels up to 1 W.

ORDERING INFORMATION	
Package	HVMDIP
Lead (Pb)-free	IRLD014PbF

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	60	V	
Gate-source voltage			V_{GS}	± 10	V	
Continuous drain current	V _{GS} at 5.0 V	$T_A = 25 ^{\circ}\text{C}$ $T_A = 100 ^{\circ}\text{C}$	- I _D	1.7		
		T _A = 100 °C		1.2	Α	
Pulsed drain current ^a			I _{DM}	14		
Linear derating factor				0.0083	W/°C	
Single pulse avalanche energy ^b			E _{AS}	490	mJ	
Maximum power dissipation	T _A = 25 °C		P_{D}	1.3	W	
Peak diode recovery dV/dt ^c			dV/dt	4.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering recommendations (peak temperature)	For 10 s			300 ^d		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. $V_{DD} = 25 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 197 \,^{\circ}\text{mH}$, $R_a = 25 \,^{\circ}\Omega$, $I_{AS} = 1.7 \,^{\circ}\text{A}$ (see fig. 12)
- c. $I_{SD} \le 10$ A, $dI/dt \le 90$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL TYP. MAX. U		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	120	°C/W	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static						l .		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	60	-	-	V		
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.070		V/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1.0	-	2.0	V	
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 10 V		-	-	± 100	nA	
Zon Oak William Burin Oamal		V _{DS} = 60 V, V _{GS} = 0 V		-	-	25		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 48 \text{ V},$	V _{GS} = 0 V, T _J = 150 °C	-	-	250	μA	
Durin On the On Older Business	Б	V _{GS} = 5.0 V	I _D = 1.0 A ^b	-	-	0.20	Ω	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 0.85 A ^b	-	-	0.28		
Forward Transconductance	9 _{fs}	V _{DS} = 25 V, I _D = 1.0 A ^b		1.9	-	-	S	
Dynamic								
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V}$ $V_{DS} = 25 \text{ V}$ f = 1.0 MHz, see fig. 5		-	400	-	pF	
Output Capacitance	Coss			-	170	-		
Reverse Transfer Capacitance	C _{rss}			-	42	-		
Total Gate Charge	Qg			-	-	8.4	nC	
Gate-Source Charge	Q _{gs}	V _{GS} = 5.0 V	$I_D = 10 \text{ A}, V_{DS} = 48 \text{ V}$ see fig. 6 and 13 ^b	-	-	2.6		
Gate-Drain Charge	Q _{gd}		see lig. 6 and 13		-	6.4		
Turn-On Delay Time	t _{d(on)}			-	9.3	-	-	
Rise Time	t _r	V_{DD}	= 30 V, I _D = 10 A	-	110	-		
Turn-Off Delay Time	t _{d(off)}	$R_g = 12 \Omega$, $R_D = 2.8 \Omega$, see fig. 10^b		-	17	-	ns -	
Fall Time	t _f			-	26	-		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.0	-		
Internal Source Inductance	L _S			-	6.0	-	- nH	
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	1.7	^	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	14	A	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 1.7 A, V _{GS} = 0 V ^b		-	-	1.6	V	
Body Diode Reverse Recovery Time	t _{rr}	T 05.00 !	10 4 41/44 400 4 / 5	-	93	130	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 10 \text{A}, dI/dt = 100 \text{A/} \mu \text{s}^{\text{b}}$		-	0.34	0.65	μC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and				L _D)		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

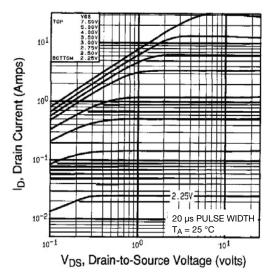


Fig. 1 - Typical Output Characteristics, T_A = 25 °C

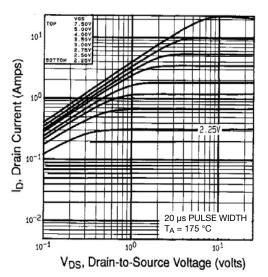


Fig. 2 - Typical Output Characteristics, T_A = 175 °C

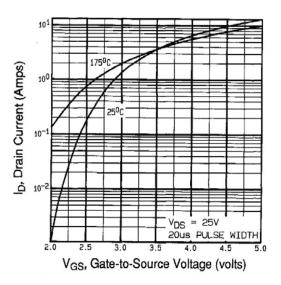


Fig. 3 - Typical Transfer Characteristics

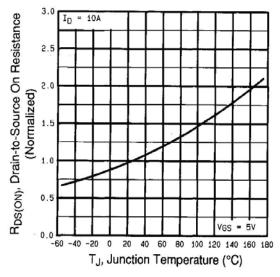


Fig. 4 - Normalized On-Resistance vs. Temperature



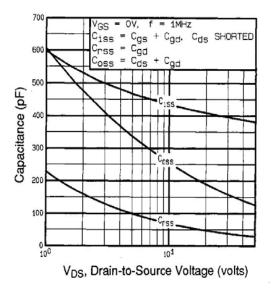


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

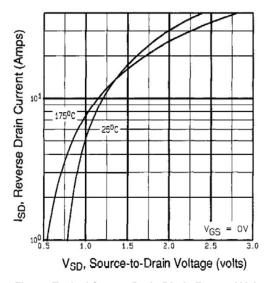


Fig. 7 - Typical Source-Drain Diode Forward Voltage

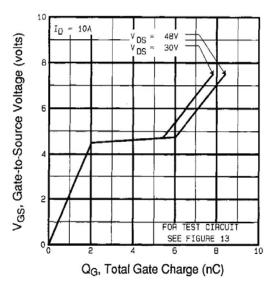


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

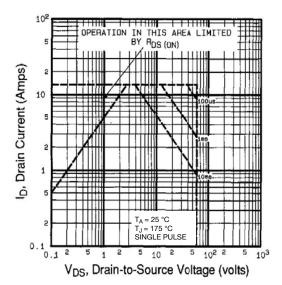


Fig. 8 - Maximum Safe Operating Area



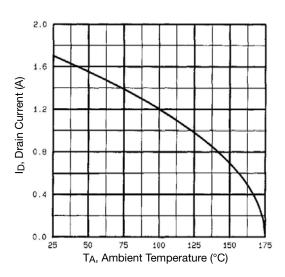


Fig. 9 - Maximum Drain Current vs. Ambient Temperature

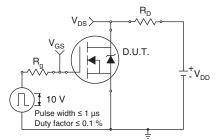


Fig. 10a - Switching Time Test Circuit

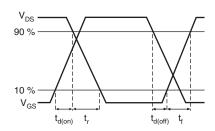


Fig. 10b - Switching Time Waveforms

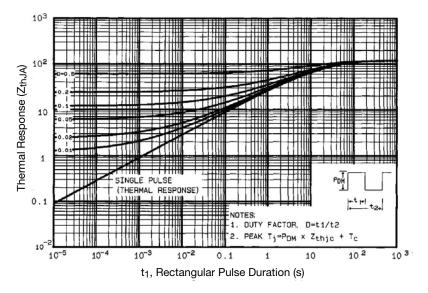


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



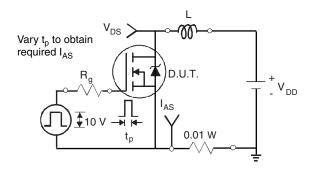


Fig. 12a - Unclamped Inductive Test Circuit

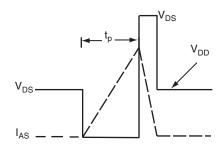


Fig. 12b - Unclamped Inductive Waveforms

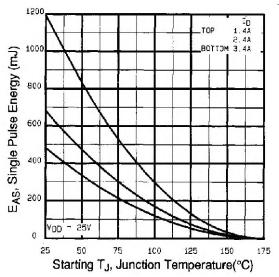


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

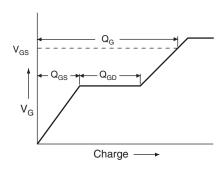


Fig. 13a - Basic Gate Charge Waveform

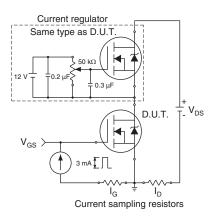
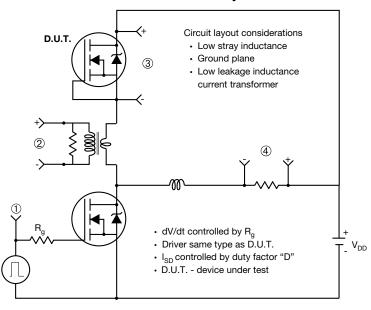


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



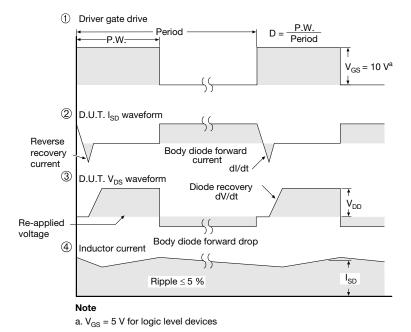


Fig. 14 - For N-Channel

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